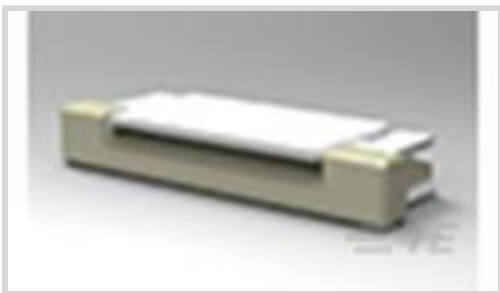




Connectors > PCB Connectors > Wire-to-Board Connectors > FFC, FPC & Ribbon Connectors > FPC Connectors



Centerline (Pitch): **.5 mm [.02 in]**

Mating Retention Type: **Zero Insertion Force (ZIF)**

PCB Mount Orientation: **Right Angle**

Contact Mating Location: **Top**

Termination Method to PCB: **Surface Mount**

Features

Product Type Features

| | |
|-----------------------------------|---|
| PCB Connector Type | PCB Mount Receptacle |
| Connector & Contact Terminates To | Flexible Printed Circuit (FPC), Printed Circuit Board |
| Connector Product Type | Connector Assembly |
| Connector System | Flex-to-Board |
| FPC Actuator Type | Stuffer |

Configuration Features

| | |
|-----------------------------------|-------------|
| Compatible With Wire & Cable Type | FFC, FPC |
| Number of Rows | 1 |
| PCB Mount Orientation | Right Angle |
| Number of Positions | 46 |

Electrical Characteristics

| | |
|-------------------|---------|
| Operating Voltage | 250 VAC |
|-------------------|---------|

Body Features

| | |
|-----------------------|---------|
| Primary Product Color | Natural |
|-----------------------|---------|

Contact Features

| | |
|---|-------------------|
| Contact Current Rating (Max) | .5 A |
| Contact Shape & Form | Single Beam |
| PCB Contact Termination Area Plating Material Thickness | .025 µm[.984 µin] |



| | |
|--|-------------------|
| Contact Layout | Inline |
| Contact Base Material | Phosphor Bronze |
| PCB Contact Termination Area Plating Material | Gold |
| Contact Type | Socket |
| Contact Mating Area Plating Material Thickness | .025 μm[.984 μin] |
| Contact Mating Location | Top |
| Contact Mating Area Plating Material | Gold Flash |

Termination Features

| | |
|---------------------------|---------------|
| Termination Method to PCB | Surface Mount |
|---------------------------|---------------|

Mechanical Attachment

| | |
|-------------------------|----------------------------|
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Retention | With |
| PCB Mount Alignment | Without |
| Mating Retention Type | Zero Insertion Force (ZIF) |

Housing Features

| | |
|--------------------|---------------|
| Housing Material | LCP |
| Centerline (Pitch) | .5 mm[.02 in] |

Dimensions

| | |
|------------------------------|--------------------|
| Connector Width | 5.1 mm[.2 in] |
| Accepts Flex Cable Thickness | .3 mm[.012 in] |
| Connector Height | 2.05 mm[.08 in] |
| Connector Length | 28.43 mm[1.119 in] |

Usage Conditions

| | |
|-----------------------------|---------------------------|
| Operating Temperature Range | -40 – 85 °C[-40 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Identification Marking

| | |
|--------------------------------|---------|
| Circuit Identification Feature | Without |
|--------------------------------|---------|

Packaging Features

| | |
|--------------------|-------------|
| Packaging Method | Tape & Reel |
| Packaging Quantity | 2000 |



Product Compliance

For compliance documentation, visit the product page on TE.com>

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUN 2018 (191) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



TE Part #1-1355880-1
AMP MCP 2.8, CONTACT LANCELESS



TE Part #1-1676913-7
YR1 0.1% 1K5



TE Part #1757819-6
AMPLIMITE,ASY,PLUG,STD,109,ZN,1, CT



TE Part #1-1571076-0
PRASA1-16F-BB0BW=POWER ROCKER



TE Part #1622412-1
LR1 1% 2K0



TE Part #1676221-2
RN 0805 1K0 0.1% 10PPM 1KRL



TE Part #1622179-1
LR0204 1% 18R2



TE Part #1623463-1
CRG1206 1% 22R



TE Part #2176343-6
CRGCQ 1206 27R 1%



TE Part #2-1879026-7
YR1 0.1% 18R2

Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_4-1734839-6_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_4-1734839-6_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_4-1734839-6_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

FPC Connector Family

English

1-1773959-7-FPC-Connectors-CN

English

Product Specifications

Product Specification

English